

50V, DC - 7.0GHz, 30W GaN HEMT

FEATURES

GTH0-0007030S

- Operating Frequency Range: DC to 7.0GHz
- Operating Drain Voltage: 28V & 50V
- Maximum Output Power (PSAT): 30W
- Air Cavity Ceramic package
- Suitable for CW, Pulsed, Linear applications
- 100% DC & RF Production Tested

DESCRIPTION



NI-200 Ceramic Package

The GTH0-0007030S is a 30W (P3dB) unmatched discrete GaN-on-SiC HEMT which operates from DC to 7.0GHz on a 50V supply rail. The wide bandwidth of the GTH0-0007030S makes it suitable for a variety of applications including cellular infrastructure, radar, communications, and test instrumentation, and can support CW, linear and pulse operations.

The device is housed in an industry-standard NI-200 Air Cavity Ceramic package. Lead-free and RoHS compliant.

Typical Performances 1 Tone pulsed CW (10% duty cycle, 100µs width), 2nd Harmonics NOT optimized

- (1) Optimum Peak Power at 2.5dB in compression
- (2) Optimum Peak Efficiency at 2.5dB in compression

Vds=50V, Idq= 30 mA, T_A = 25°C

Frequency (MHz)	Pout ⁽¹⁾ (dBm)	Gain ⁽²⁾ (dB)	Eff ⁽²⁾ (%)
2000	45.5	20.8	65.2
2500	45.4	18.4	61.7
3000	45.4	17.6	66.5
3500	45.5	16.4	67.5
4000	45.5	15.7	67.6
4500	45.5	15.4	67
5000	45.7	14.9	68.4

Vds=28V, Idq= 30 mA, T_A = 25°C

Frequency (MHz)	Pout ⁽¹⁾ (dBm)	Gain ⁽²⁾ (dB)	Eff ⁽²⁾ (%)
2000	43	18.5	67
2500	42.9	16.9	67.1
3000	42.9	15.8	69.6
3500	43	14.5	69.8
4000	43	13.6	69.5
4500	43	12.6	69.3
5000	43.1	12.5	69.7

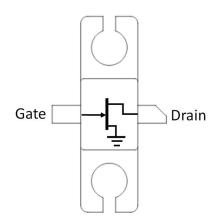


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BLOCK DIAGRAM

ABSOLUTE MAXIMUM RATINGS^(1, 2)

Parameter	Rating	Symbols and Units
Drain Source Voltage	150	$V_{DS}(V)$
Gate Source Voltage	-8 to +2	V _{GS} (V)
Operating Voltage	55	V _{dsq} (V)
Junction Temperature	+225	T _{JUNC} (°C)
Storage Temperature	-65 to +150	T _{STORAGE} (°C)
Case Operating Temperature	-40 to +105	T _{CASE} (°C)



1. Exceeding any of these limits may cause permanent damage to this device or seriously limit the life time (MTTF)

2. GalliumSemi does not recommend sustained operation above maximum operating conditions.

ELECTRICAL SPECIFICATIONS: T_A = 25°C

Parameter	Min.	Тур.	Max.	Symbols and Units	Test conditions		
Frequency Range	DC		7000	MHz			
DC Characteristics							
Drain Source Breakdown Voltage	150			V _{BDSS} (V)			
Drain Source Leakage Current				I _{DLK} (mA)	Vgs = -8V, Vds = 50V		
Gate Source Leakage Current				I _{GLK} (mA)	Vgs = -8V, Vds = 50V		
Gate Threshold Voltage	-3.4		-1.5	V _{GS} (V)	Vds = 50V		
Operating Conditions							
Gate Bias Voltage		-2.5		V _{GSQ} (V)			
Drain Voltage		50		V _{DSQ} (V)			
Quiescent Drain Current		30		I _{DQ} (mA)			



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RF ELECTRICAL SPECIFICATIONS: $T_A = 25^{\circ}C$, VDS = 50 V, IDQ = 30 mA, Freq= 3600MHz Note: Performance⁽¹⁾ in GalliumSemi Production Test Fixture, 50 Ω system

Parameter	Symbol	Min.	Тур.	Max.	Units	Notes
Small Signal Gain	G _{ss}		tbd		dB	
Power Gain	G _{SAT}		tbd		dB	
Saturated Drain Efficiency	DEff _{SAT}		tbd		%	
Saturated Output Power	P _{SAT}		tbd		dBm	
Ruggedness Output mismatch	Ψ	VSWR =	= 10:1, all ar	ngles		No damage or shift in performances

1. 1 Tone Pulse CW, pulse width 100us, duty cycle 10%



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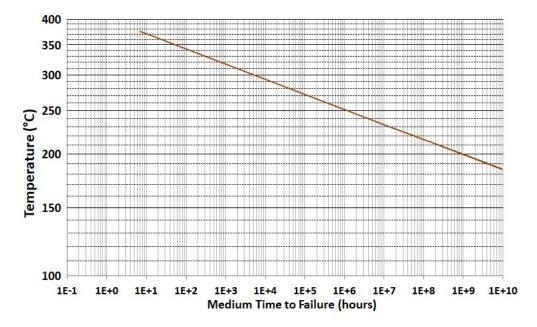
THERMAL AND RELABILITY INFORMATION -CW ^(1, 2, 3): T_c = 85°C

Parameter	Test condition	Value	Units	Notes
Channel Temperature, Tch		135	°C	
Rth	Pdiss 6 W	8.3	°C/W	
MTTF	_	>1.0E10	Hrs	
Channel Temperature, Tch		192	°C	
Rth	Pdiss 12 W	9.0	°C/W	
MTTF		3.2E9	Hrs	
Channel Temperature, Tch		258	°C	
Rth	Pdiss 18 W	9.6	°C/W	
MTTF		5.0E5	Hrs	

1.Using 5um thermal grease - 4W/m-K.

2. Thermal Resistance using Finite Element Analysis (FEA) simulation, calibrated with Infrared measurement on surface temperature.

3.Rth vs Dissipated Power can be generalized with the following equation: Rth(°C/W) = 0.1065 x Pdiss(W) + 7.8704





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CW OPERATION

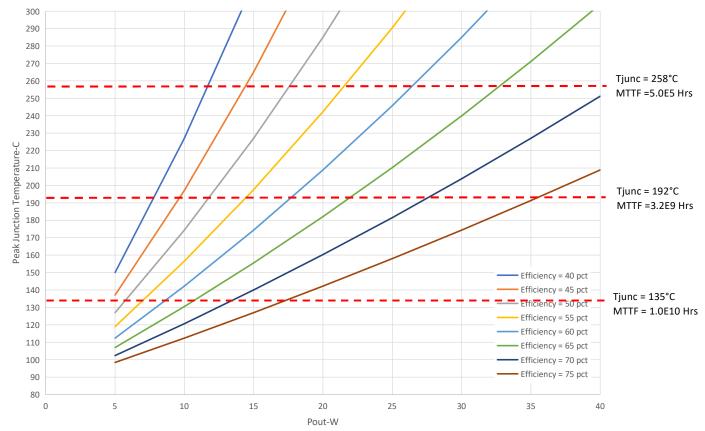
The device can withstand CW operation with respect to the application's MTTF (Life time vs. Peak Junction Temperature).

The graph(1,2) below shows the Peak Junction Temperature vs. the Output Power & Efficiency trade-off, using the following equations:

- Tjunc(°C) = Pdiss(w) x Rth(°C/W)

- Pdiss(W) = (Pout(w)/ Efficiency(%)) - Pout(w)

E.g.: The device can be used for Pout = 22W CW with Efficiency of 55%, Tjunc will be 258°C, leading to a LifeTime (MTTF) of 5.0E5 Hrs.



Notes: 5um thermal grease - 4W/m-K Back of pkg is 85°C infinite heat sink



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LOADPULL MEASUREMENT, Vds= 50V ldq = 30 mA

1 Tone Pulse CW, pulse width 100us, duty cycle 10%

For Optimum Peak Power @ 2.5dB Compression							
Freq-MHz	Zin_F0	ZI_F0	Gain-dB	Pout-dBm	Pout-W	Eff-%	AMPM-deg
2000	3.3 j -3.4	18.0 j 10.5	19.3	45.5	35.8	57.7	0.9
2500	3.2 j 1.8	16.6 j 9.1	17.5	45.4	34.7	56.1	0.2
3000	3.9 j 6.2	15.2 j 4.2	15.4	45.4	34.4	53.7	0.3
3500	3.9 j 10.4	12.7 j 3.6	14.8	45.5	35.6	57.6	-1.4
4000	4.3 j 14.3	12.3 j 0.3	13.6	45.5	35.4	55.8	-1.2
4500	5.0 j 20.5	10.1 j -1.7	13.3	45.5	35.9	58.8	-1.6
5000	5.8 j 28.5	8.7 j -3.9	13.1	45.7	37.1	62.6	-1.5

		For Optimum	Peak Efficiend	cy @ 2.5dB Com	npression		
Freq-MHz	Zin_F0	ZI_F0	Gain-dB	Pout-dBm	Pout-W	Eff-%	AMPM-deg
2000	2.2 j -1.3	14.2 j 22.6	20.8	43.8	24	65.2	0.7
2500	2.4 j 2.7	14.1 j 19.4	18.4	44.3	27.1	61.7	1
3000	2.2 j 7.8	8.7 j 13.6	17.6	44	25.2	66.5	-2.7
3500	2.7 j 11.0	7.0 j 9.0	16.4	44.1	26	67.5	-4.4
4000	3.0 j 15.6	6.0 j 5.4	15.7	44.1	25.5	67.6	-4.4
4500	3.1 j 21.4	5.1 j 2.2	15.4	43.8	23.9	67	-4.2
5000	4.0 j 29.9	5.3 j -0.9	14.9	44.3	27.2	68.4	-2.8



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LOADPULL MEASUREMENT, Vds= 28V Idq = 30 mA

1 Tone Pulse CW, pulse width 100us, duty cycle 10%

For Optimum Peak Power @ 2.5dB Compression							
Freq-MHz	Zin_F0	ZI_F0	Gain-dB	Pout-dBm	Pout-W	Eff-%	AMPM-deg
2000	3.0 j -3.0	15.2 j 3.1	17.5	43	20.3	60.7	1.2
2500	3.5 j 2.1	16.8 j -0.4	15.2	42.9	19.4	58	0.9
3000	2.9 j 7.3	12.3 j 1.3	14.7	42.9	19.7	64.6	-1.8
3500	3.8 j 11.2	10.8 j -3.1	13	43	20	60.2	-2.1
4000	4.3 j 15.9	11.3 j -5.2	12.3	43	19.8	60.5	-2.9
4500	5.0 j 22.0	11.2 j -7.3	11.5	43	20.1	60.9	-2.8
5000	6.1 j 30.9	10.7 j -9.2	11.4	43.1	20.5	63.2	-3.2

		For Optimum	Peak Efficien	cy @ 2.5dB Cor	npression		
Freq-MHz	Zin_F0	ZI_F0	Gain-dB	Pout-dBm	Pout-W	Eff-%	AMPM-deg
2000	2.3 j -1.7	16.1 j 14.8	18.5	41.3	13.5	67	1.6
2500	2.5 j 2.8	13.3 j 9.0	16.9	42.1	16.3	67.1	-1.4
3000	2.2 j 8.7	9.5 j 7.9	15.8	41.3	13.4	69.6	-3.8
3500	2.6 j 11.9	7.8 j 4.0	14.5	41.4	13.8	69.8	-5.5
4000	2.9 j 16.7	7.2 j 0.9	13.6	41.4	13.8	69.5	-5.7
4500	3.8 j 22.3	6.3 j -2.6	12.6	41.5	14.2	69.3	-7.2
5000	4.6 j 31.0	5.2 j -6.0	12.5	41.2	13.3	69.7	-7.7



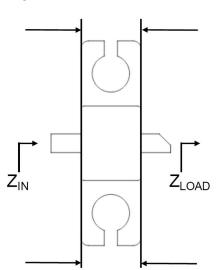
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LOADPULL MEASUREMENT NOTES

Source and Load impedance @ 2nd Harmonic are set to 10 Ohms

With proper 2nd Harmonic termination, expect +5% Efficiency for Source and similar with Drain 2nd Harmonic.

 Z_{LOAD} : Measured Impedance presented to the output of the device in the reference plane Z_{IN} : Measured input Impedance at the input of the device in the reference plane



Impedance Reference Plane

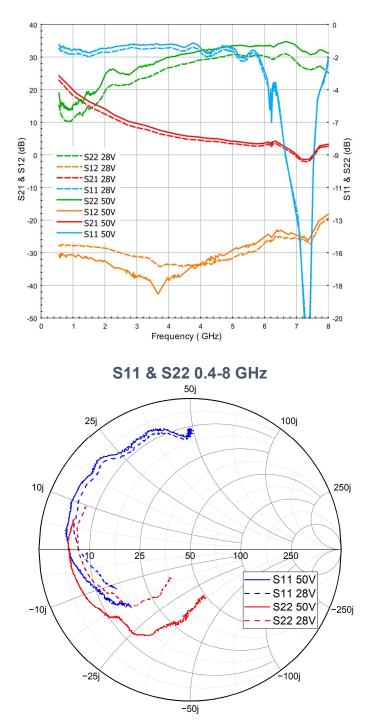
Raw data and full Loadpull measurement report available at request: sales@galliumsemi.com



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BROADBAND S-PARAMETERS MEASUREMENT, Vds= 28 & 50V ldq = 30 mA 1 Tone CW

S Parameters (Mag-dB)

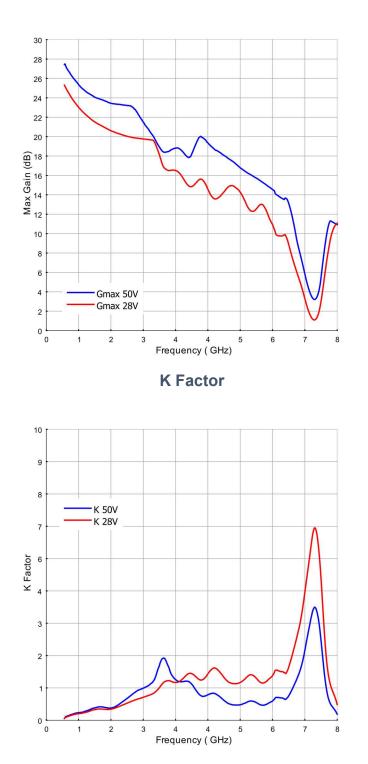




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BROADBAND S-PARAMETERS MEASUREMENT, Vds= 28 & 50V ldq = 30 mA 1 Tone CW

Maximum Available Gain





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GaN HEMT BIASING SEQUENCE

To turn the transistor ON

- 1. Set V_{GS} to -5V
- 2. Turn on V_{DS} to normal operation voltage (50V)
- 3. Slowly increase VGs to set IDQ current (30 mA)
- 4. Apply RF power

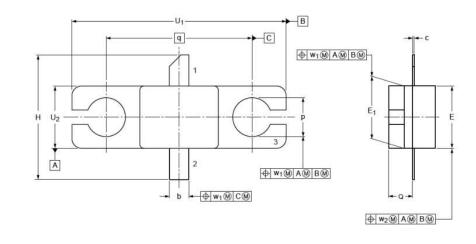
To turn the transistor OFF

- 1. Turn the RF power off
- 2. Decrease V_{GS} to -5V
- 3. Turn off V_{D.} Wait a few seconds for drain capacitor to discharge
- 4. Turn off V_{GS}



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PACKAGE DIMENSIONS



Dimen	sions	ns 0 5 mm scale															
Uni	t(1)	А	b	с	D	D ₁	Е	E ₁	F	н	р	Q	q	U1	U ₂	w ₁	w ₂
mm	max nom	3.68	1.40	0.15	5.18	5.21	4.17	4.19	1.14	8.64	2.67	1.70	9.53	14.10	4.19	0.25	0.380
	min	2.84	1.14	0.08	4.98	4.95	3.96	3.94	0.89	7.62	2.41	1.45	0.00	13.84	3.94	0.00	
inches		0.145	0.055	0.006	0.204	0.205	0.164	0.165	0.045	0.340	0.105	0.067	0.375	0.555	0.165	0.01	0.015
	min	0.112	0.045	0.003	0.196	0.195	0.156	0.155	0.035	0.300	0.095	0.057	0.010	0.545	0.155		

Note 1. Millimeter dimensions are derived from the original inch dimensions.

PIN CONFIGURATION

DEVICE LABEL

Pin	Input/Output
1	RF Output / Drain Voltage
2	RF Input / Gate Voltage
3 (flange)	Ground

Line 1:	COMPANY NAME: GALLIUM		
Line 2:	PART NUMBER - WAFER #		
Line 3:	AA:	Assembly Code	
	YYWW:	Assembly Date Code	
	R:	Reserved code	



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HANDLING PRECAUTIONS

Parameter	Symbol	Class	Test Methodology
ESD-Human Body Model	HBM	Class 1A (250 V)	ANSI/ESDA/JEDEC Standard JS-001
ESD-Charged Device Model	CDM	Class C3 (1500 V)	ANSI/ESDA/JEDEC Standard JS-002
MSL–Moisture Sensitivity Level	MSL	MSL 1	IPC/JEDEC Standard J-STD-020



RoHS COMPLIANCE

Gallium Semiconductor's Policy on EU RoHS available online: https://www.galliumsemi.com/ files/ugd/3748d3 1107b9788f9845f78f45d424097c4c97.pdf



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CONTACT INFORMATION

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